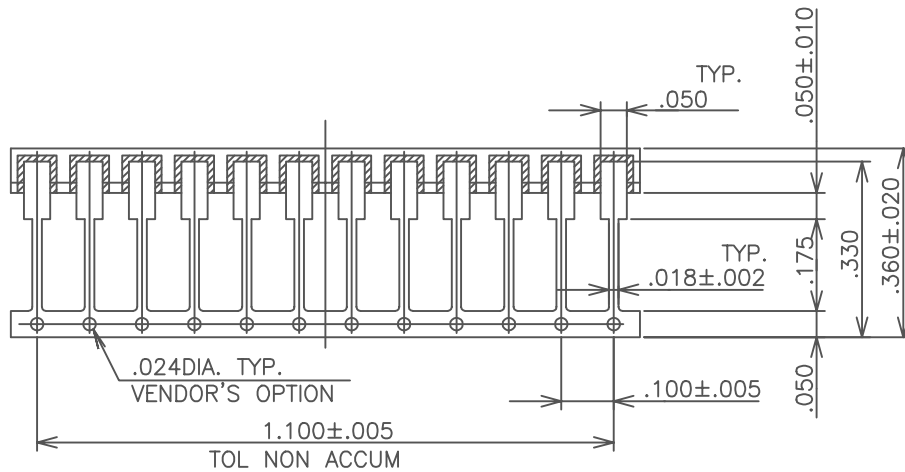


PART NO.	INDEX MARK	LEAD TIED DOWN
01		NIL
02		PIN NO.1 ONLY



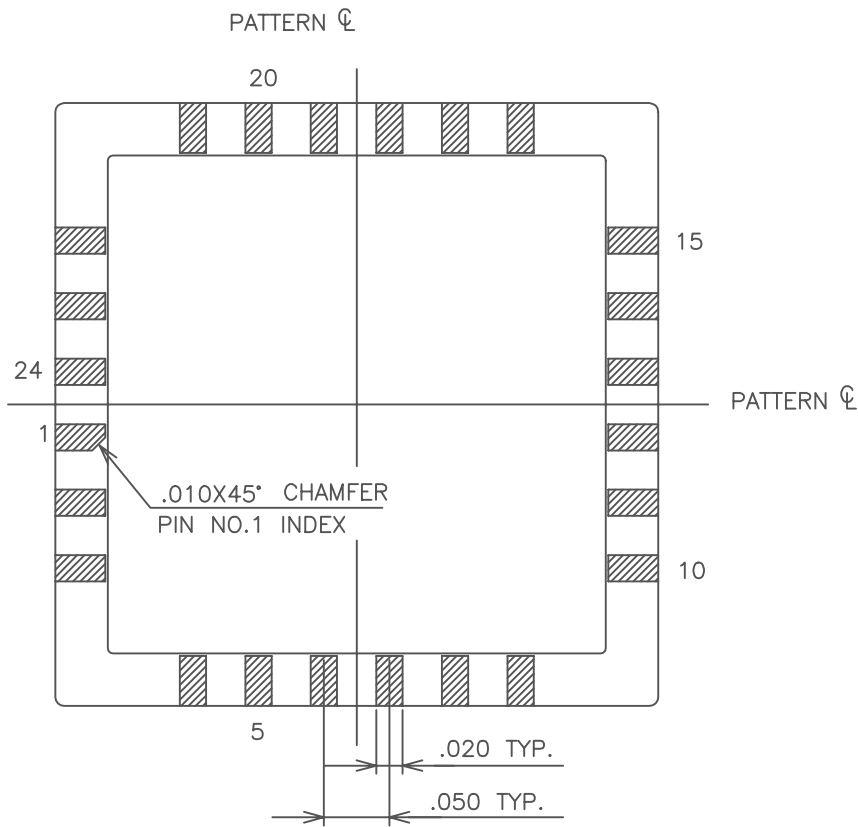
DETAIL-A

NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. LEAD RESISTANCE: 0.30 OHM MAX.

SB024I516-2	S=0 D=1
SB024I516-1	S=0 D=0

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	S.S	K.M	T.A	DEC.04.'78
					SCALE 4/1	MATERIAL AS INDICATED	±.005				
							THIRD ANGLE PROJECTION				
	REDRAWN (CONVERTED CAD DATA)	AUG.21.'93	S.SH	H.S/S.F	T.A		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			KD-78516-C	1/2		



BONDING PATTERN

MODIFICATION						NAME 24 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN M.K	CHECKED S.T S.F	APPROVED T.A	DATE APR.07.'93
						SCALE 10 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
	△ REDRAWN (CONVERTED CAD DATA)	AUG.21.'93	S.SH	H.S/S.F	T.A	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-78516-C	SHEET 2/2			
	CHANGED	DATE	DRAWN	CHECKED	APPROVED						